Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A circuit board manufacturing method, comprising:

forming a transfer chip on and above a first substrate, the transfer chip having (1) a bottom adjacent the first substrate, (2) a thin-film electrical circuit formed of stacked films above the first substrate and the bottom ~~and (2)~~and (3) a plurality of transfer chip pad electrodes formed above the stacked films, ~~each having a first substantially common height from the bottom of the transfer chip, the plurality of transfer chip~~the pad electrodes including a first pad electrode having a first top positioned at a highest level within the first pad electrode and a second pad ~~electrode~~ electrode having a second top positioned at a highest level within the second pad electrode, the first pad electrode having a first height measured from the bottom of the transfer chip to the first top of the first pad electrode, and the second pad electrode having a second height measured from the bottom of the transfer chip to the second top of the second pad electrode;

forming a transfer region on a second substrate, the transfer region having (1) electrical circuit wiring and (2) a plurality of transfer region pad electrodes connected to the electrical circuit wiring;

adjusting ~~the height~~ at least one of the first ~~pad electrode~~height and the second ~~pad electrode~~height by adding at least one height adjusting ~~films;~~film so that the first height becomes substantially the same as the second height; and

joining the transfer chip to the transfer region on the second substrate, such that the thin-film electrical circuit is electrically connected to the electrical circuit wiring via ~~respective~~ contact between respective ones of ~~each of~~ the transfer chip pad electrodes and ~~each of~~ the transfer region pad electrodes.

2. (Previously Presented) The circuit board manufacturing method according to claim 1,

the plurality of transfer region pad electrodes including a third pad electrode and a fourth pad electrode,

the joining of the transfer chip being carried out such that the first pad electrode contacts the third pad electrode.

3. (Previously Presented) The circuit board manufacturing method according to claim 2,

the joining of the transfer chip being carried out such that the second pad electrode contacts the fourth pad electrode.

4. (Currently Amended) The circuit board manufacturing method according to claim 1,

the plurality of transfer region pad electrodes including (1) a third pad electrode that has a ~~third part~~third top positioned at a highest level within the third pad electrode, the third pad electrode having a third height measured from a bottom of the transfer region to the third top,~~-~~ ~~from a bottom of the~~ and (2) a fourth pad electrode that has a ~~fourth part~~fourth top positioned at a highest level within the fourth pad electrode, the fourth pad electrode having a fourth height measured from the bottom of the transfer region to the fourth top, ~~from the bottom of the transfer region,~~ and

the third ~~part~~height and the fourth ~~part~~height ~~having~~ being different ~~heights~~from each other. ~~from the bottom of the transfer region.~~

5. (Currently Amended) The circuit board manufacturing method according to claim 4,

wherein the first height of the first pad electrode is adjusted by a first amount and the second height of the second pad electrode is adjusted by a second amount, and the joining of the transfer chip being carried out such that the first pad electrode and the second pad electrode contact the third pad electrode and the fourth pad electrode, respectively,

the first amount and the second amount being selected ~~such after joining~~such that, after joining, the transfer chip and the transfer region maintain a common horizontal level.

6-11. (Canceled)

12. (Withdrawn-Currently Amended) A circuit board ~~transfer chip serving as a transfer unit~~ manufactured by the method of claim 1.

13. (Withdrawn) An electro-optical device manufactured using a circuit board manufactured by the manufacturing method as set forth in claim 1.

14. (Withdrawn) An electronic apparatus, comprising:

the electro-optical device as set forth in claim 13 usable as a display unit.

15. (Previously Presented) A method for manufacturing an electro-optical device, comprising:

a circuit board manufacturing method according to claim 1.